

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	113	(thermally adj conductive adj epoxy) and (heat adj (spreader or sink)) and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:15
L2	14	((thermally adj conductive adj epoxy) near adhesive) and (heat adj (spreader or sink)) and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:33
L3	2	"6414849".pn. and conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:36
L4	2	"6414849".pn. and conductive and thermal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:36
L5	11	(thermally adj conductive adj epoxy) and (heat adj (spreader or sink)) and (flip adj chip) and dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:38
L6	13	((al or aluminum) near (heat adj (spreader or sink))) and dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:57
L7	149	((al or aluminum) with (heat adj (spreader or sink))) and dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:57
L8	51	((al or aluminum) with (heat adj (spreader or sink))) and dam and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:03

L9	1	"20020144775".pn. and aluminum and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:03
L10	1	((thermally adj conductive adj epoxy) near dam) and (heat adj (spreader or sink)) and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:15
L11	1	((thermally adj conductive adj epoxy) near dam) and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:16
L12	3	((thermally adj conductive adj epoxy) with dam) and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:16
L13	1	((thermally adj conductive adj epoxy) near dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:17
L14	3	((thermally adj conductive adj epoxy) with dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:17
L15	3	((thermally adj conductive adj epoxy) same dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:18
L16	60	((conductive adj epoxy) same dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:18

L17	36	((conductive adj epoxy) with dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:30
L18	1	((conductive adj epoxy) near dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:19
L19	1	((thermally adj conductive) near dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31-10:30
L20	41	((thermally adj conductive) with dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:32
L21	26	((thermally adj conductive) with dam) and epoxy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 11:24
L22	2	"6294406".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 11:24
S1	8	(flip adj chip adj package) and carrier and chip and bumps and dam and (heat adj spreader)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 20:45
S2	7	(flip adj chip adj package) and carrier and chip and bumps and dam and (heat adj spreader) and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 18:55

S3	1	"6534859".pn. and dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:20
S4	1502	257/777.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:30
S5	2386	257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:31
S6	1852	257/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:31
S7	1597	257/738.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:33
S8	477	257/793.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:33
S9	710	257/796.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:34
S10	528	257/667.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:34

S11	1	"6414849".pn. and (heat adj spreader)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:54
S12	1	"6414849".pn. and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:58
S13	8	(flip adj chip adj package) and carrier and chip and bumps and dam and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:52
S14	1	"6562656".pn. and (heat adj spreader)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:54
S15	1	"6562656".pn. and (heat)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 19:54
S16	0	"6534859".pn. and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 20:19
S17	1	"6534859".pn. and (cu or copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 20:20
S18	1	"6534859".pn. and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 20:23

S19	1	"6534859".pn. and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 20:23
S20	2	carrier and chip and bumps and dam and (heat adj (spreader or sink)) and (encapsulat\$ near underfill)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:01
S22	20	((cu or copper) adj heat adj (spreader or sink)) and dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:07
S23	11	((al or aluminum) adj heat adj (spreader or sink)) and dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:55
S24	0	"5776512".pn. and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:20
S25	520	(heat adj (spreader or sink)) and dam and chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:36
S26	2	(heat adj (spreader or sink)) near attached near dam and chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:36
S27	13	(heat adj (spreader or sink)) near connected near dam and chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:39

S28	13	(heat adj (spreader or sink)) near connected near dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:43
S29	67	epoxy near dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:46
S30	1	(thermally adj conductive adj epoxy) near dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:46
S31	3	(thermally adj conductive adj epoxy) with dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:48
S32	3	(thermally adj conductive adj epoxy) same dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:49
S33	4	(thermally near conductive near epoxy) same dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 21:49
S34	1	"20020144775".pn. and dam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:26